



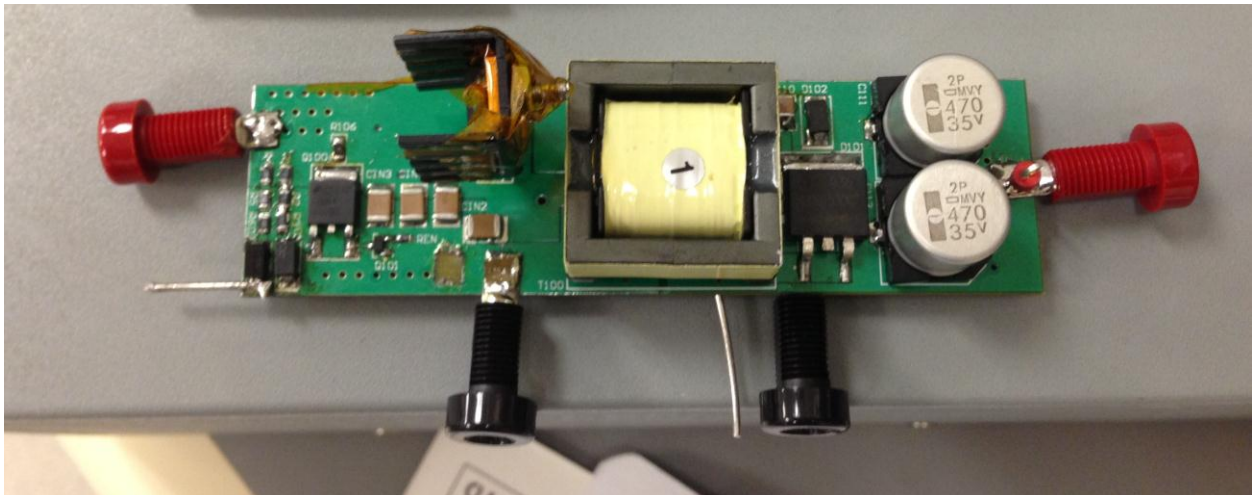
**Test Data
For PMP7958
5/21/2013**

Vin	300VDC to 600VDC
Vout	20VDC
Iout Max.	1.5A
Fsw	80 kHz

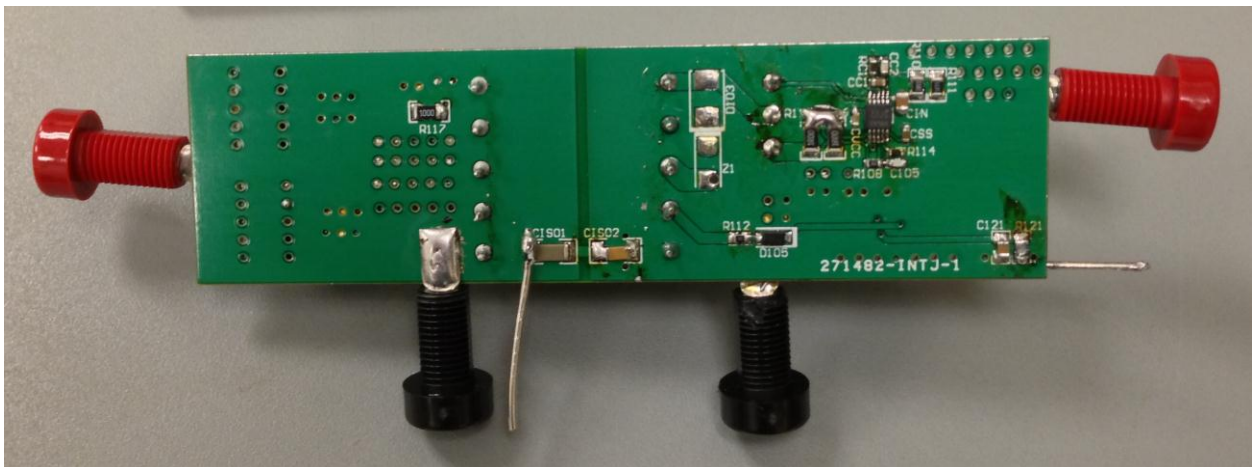
FABRICATION

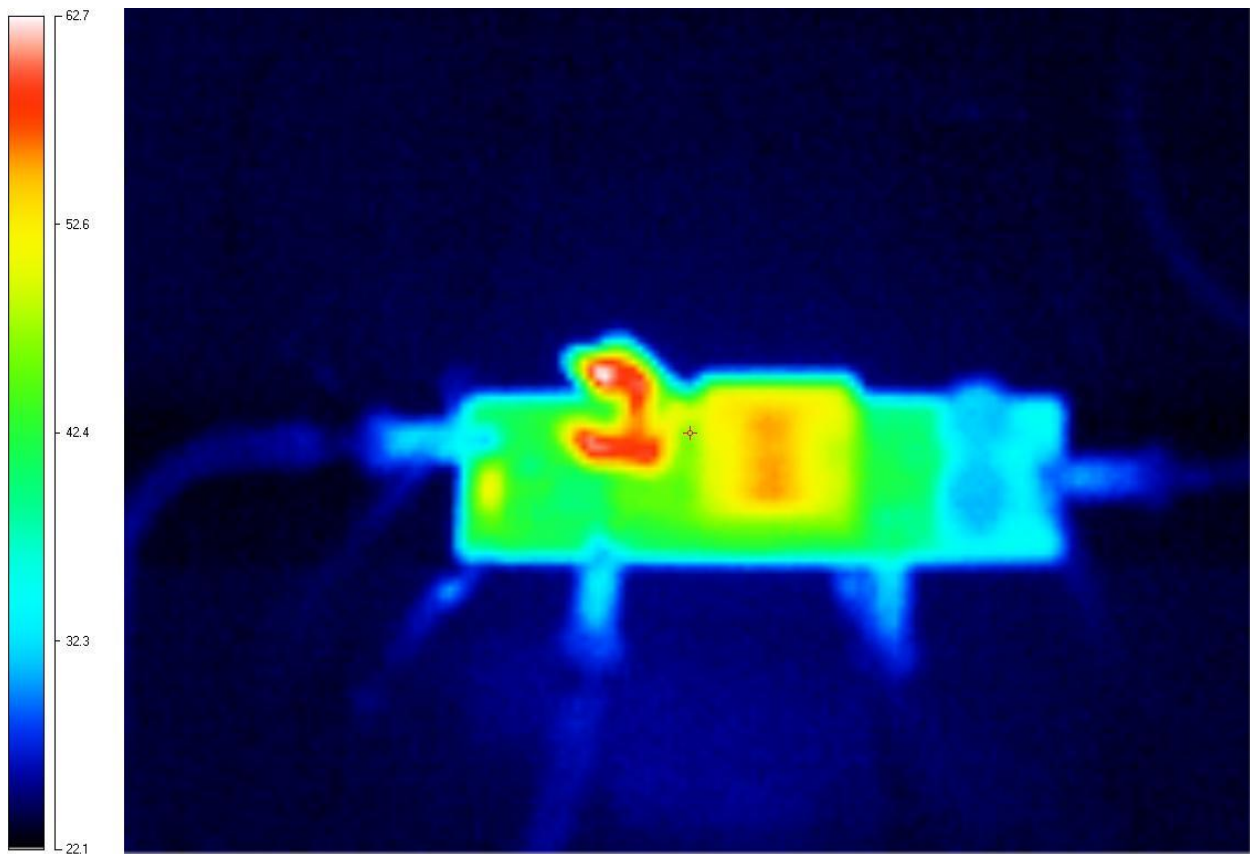
Board Dimensions: 4 "x 1.1"

Top Side

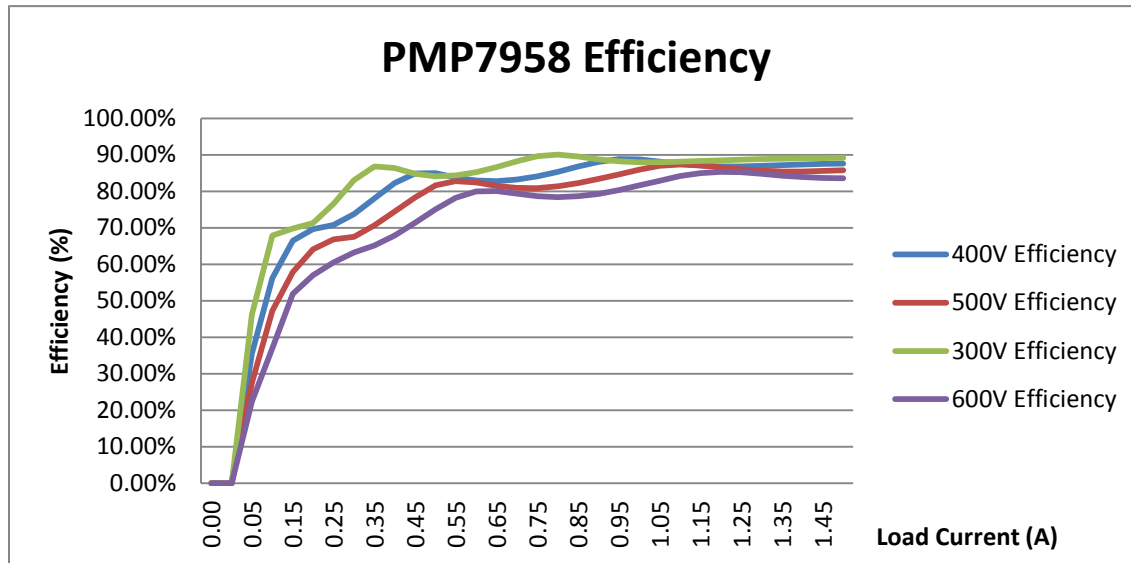
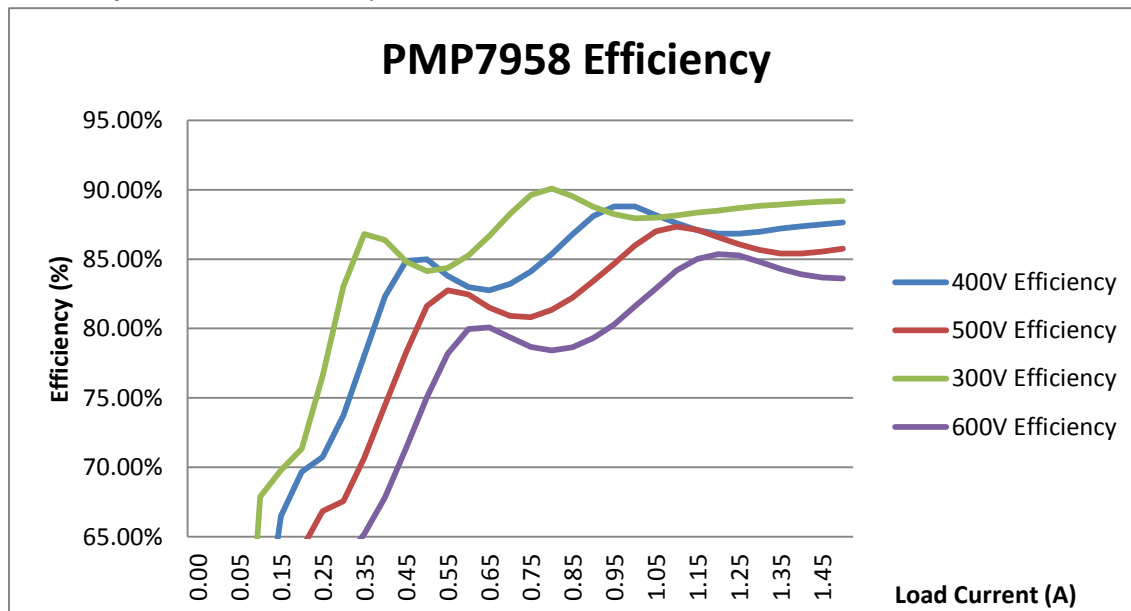


Bottom Side



Thermal Image

The thermal image was taken with the input voltage at 600V, and the load set to 1.5 Amps. The board was left running for twenty minutes. The PCB had a consistent temperature of 32°C to 42°C. The MOSFET operated close to 63°C.

Efficiency Curve Data

Efficiency Curve Data (Close up)


Load Transient at 300V_{in}; I_{out} Transient from 0.5A -1.5A



Load Transient at 400V_{in}; I_{out} Transient from 0.5A -1.5A



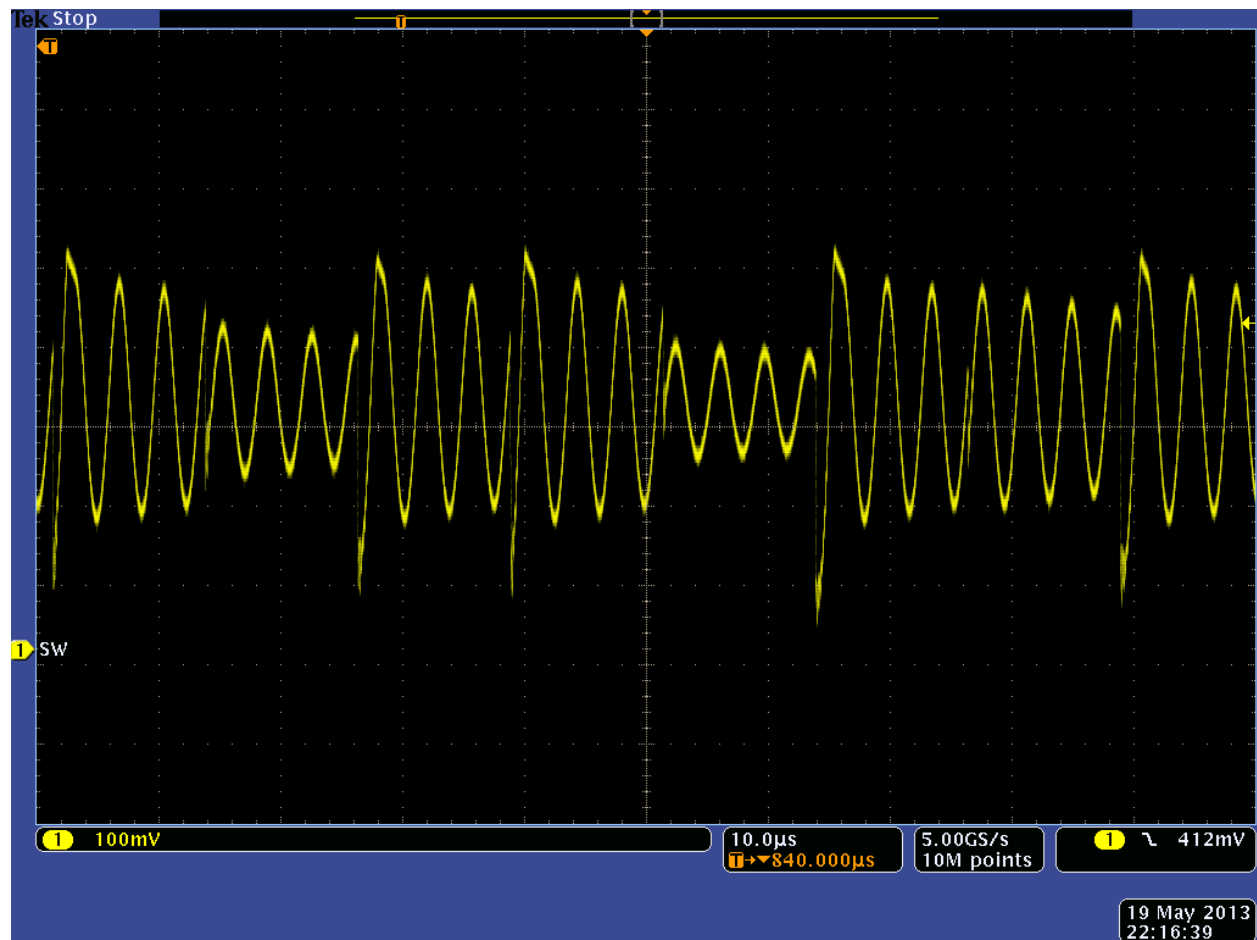
Load Transient at 500V_{in}; I_{out} Transient from 0.5A -1.5A



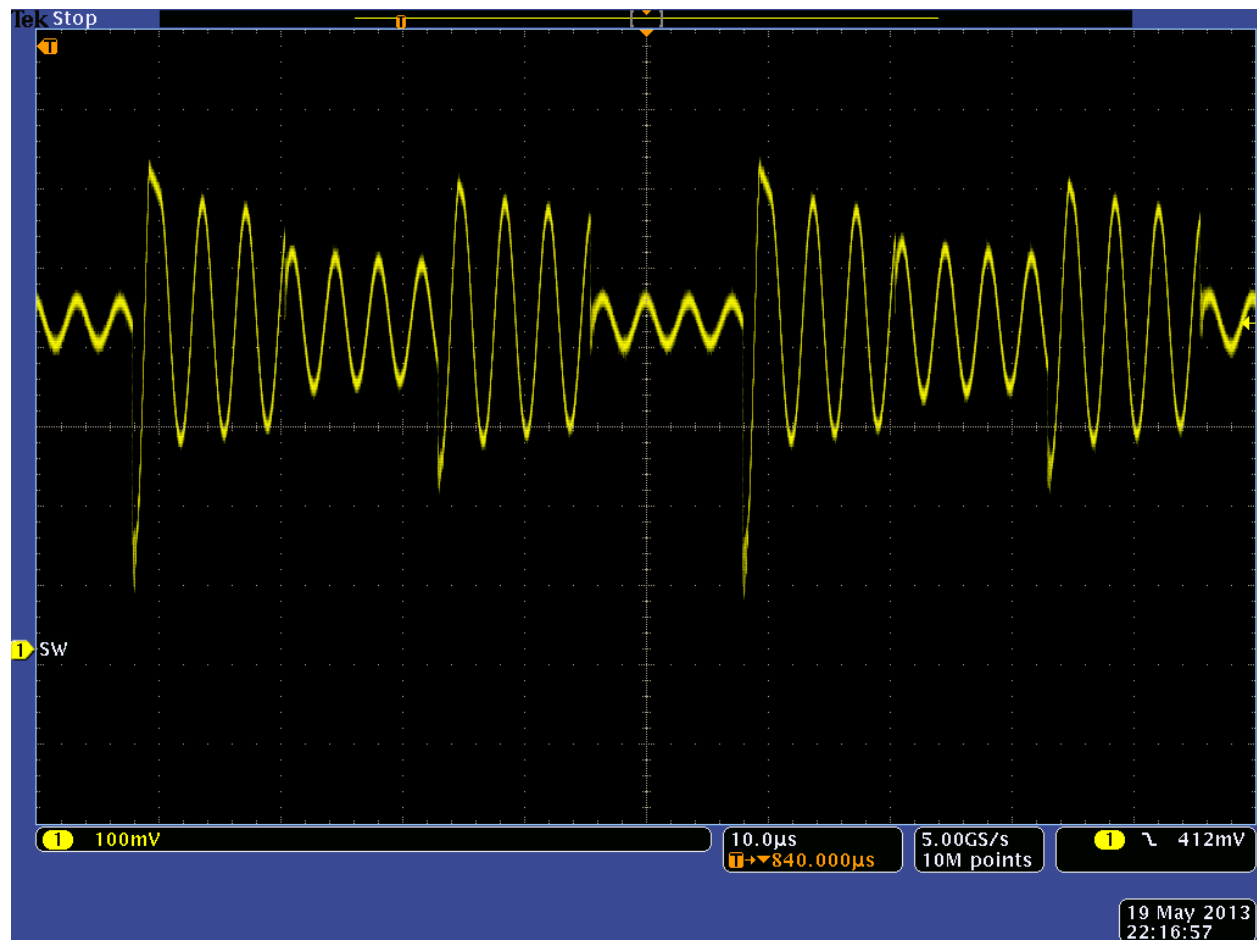
Load Transient at 600V_{in}; I_{out} Transient from 0.5A -1.5A



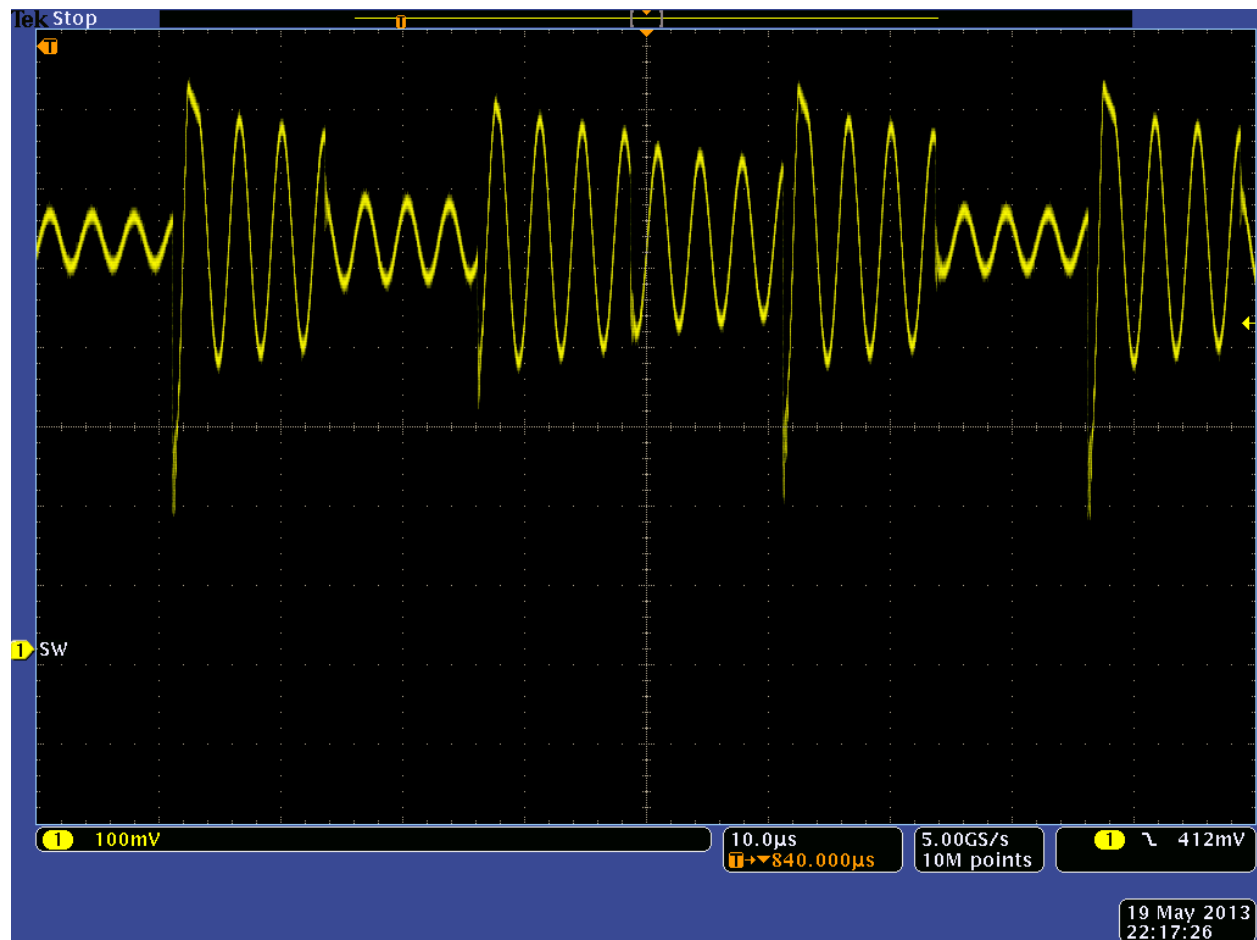
SW at 300V_{in}; 0A Load; (High Voltage probes used to attenuate signal; 1,000x Attenuation)



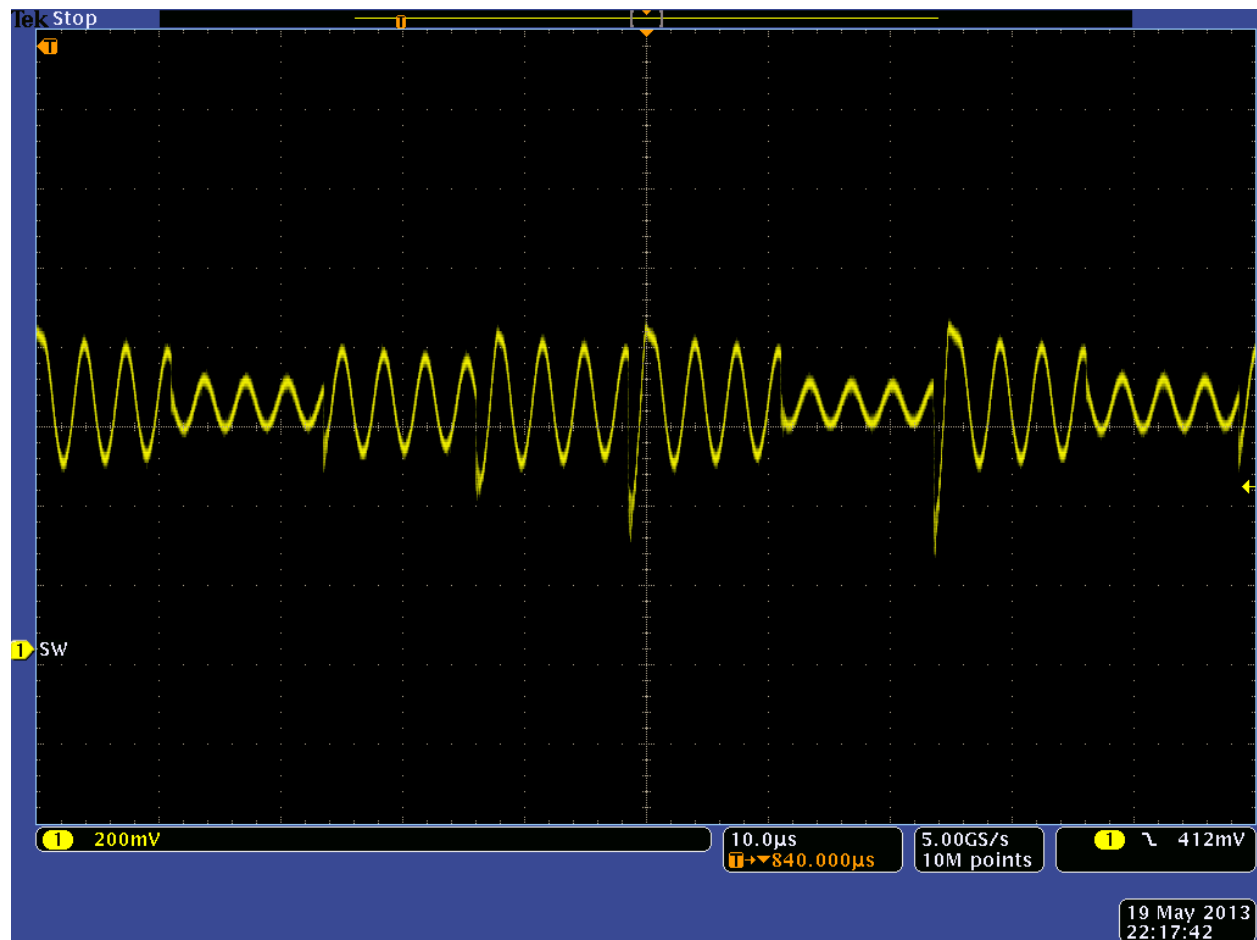
SW at 400Vin; 0A Load; (High Voltage probes used to attenuate signal; 1,000x Attenuation)



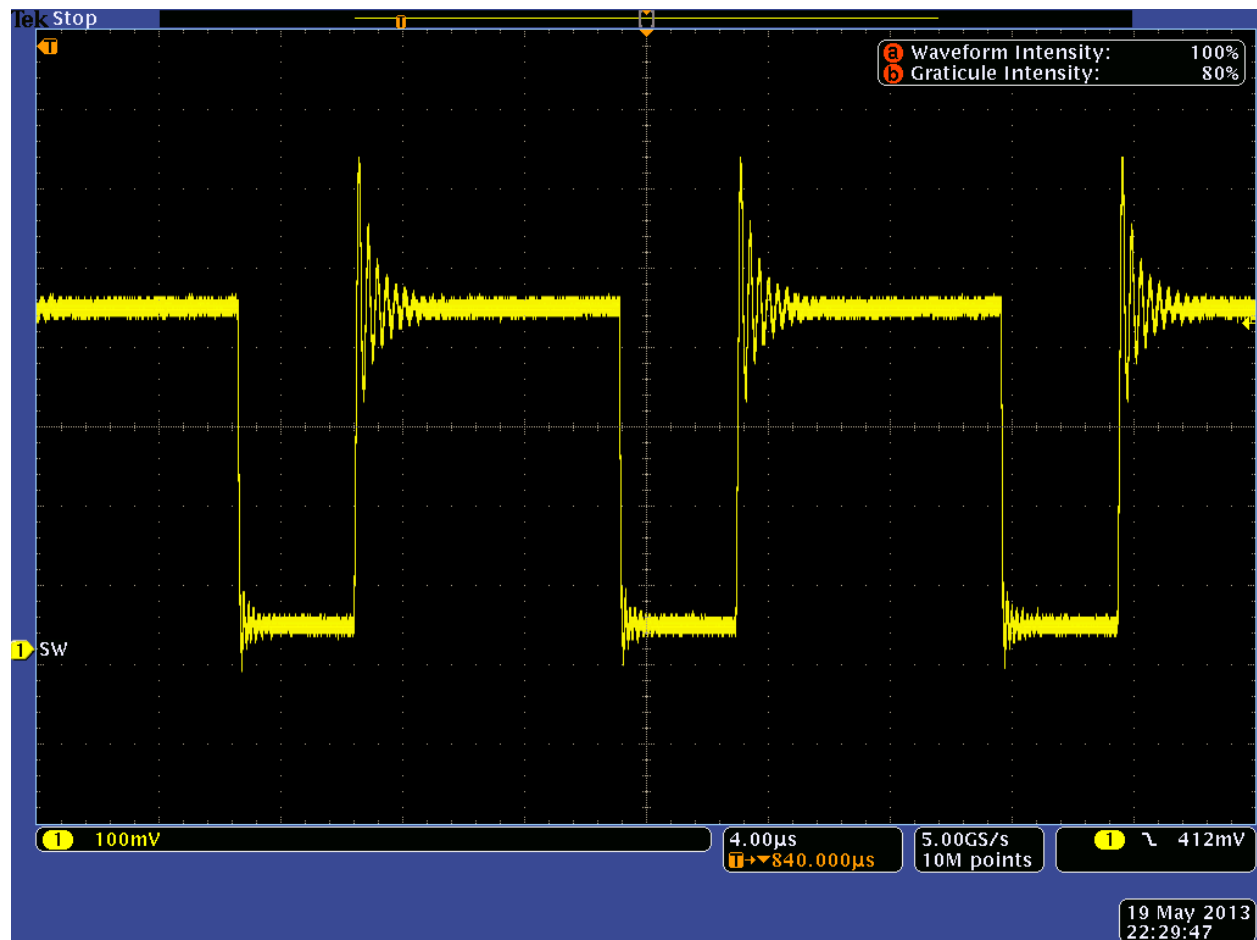
SW at 500Vin; 0A Load; (High Voltage probes used to attenuate signal; 1,000x Attenuation)



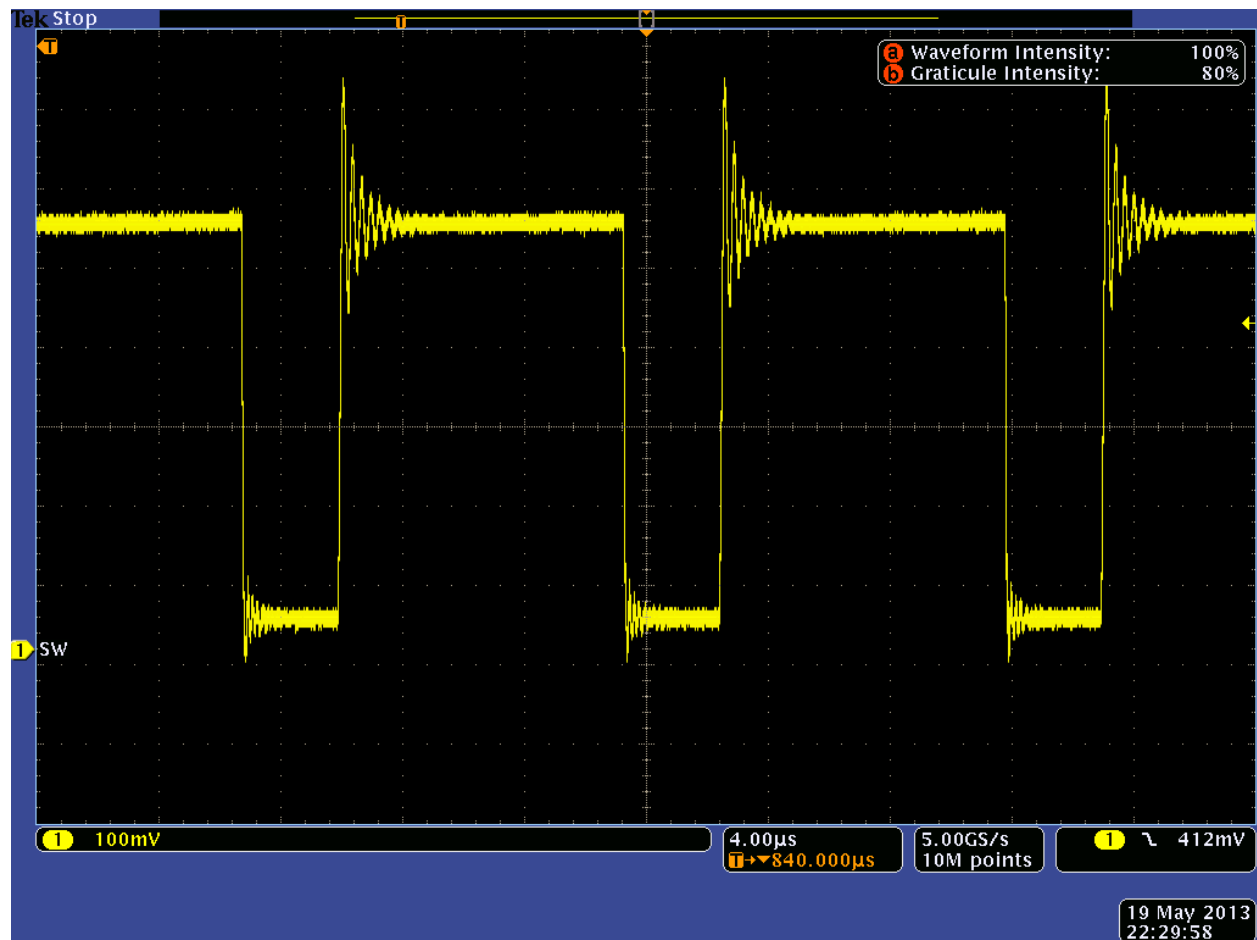
SW at 600Vin; 0A Load; (High Voltage probes used to attenuate signal; 1,000x Attenuation)



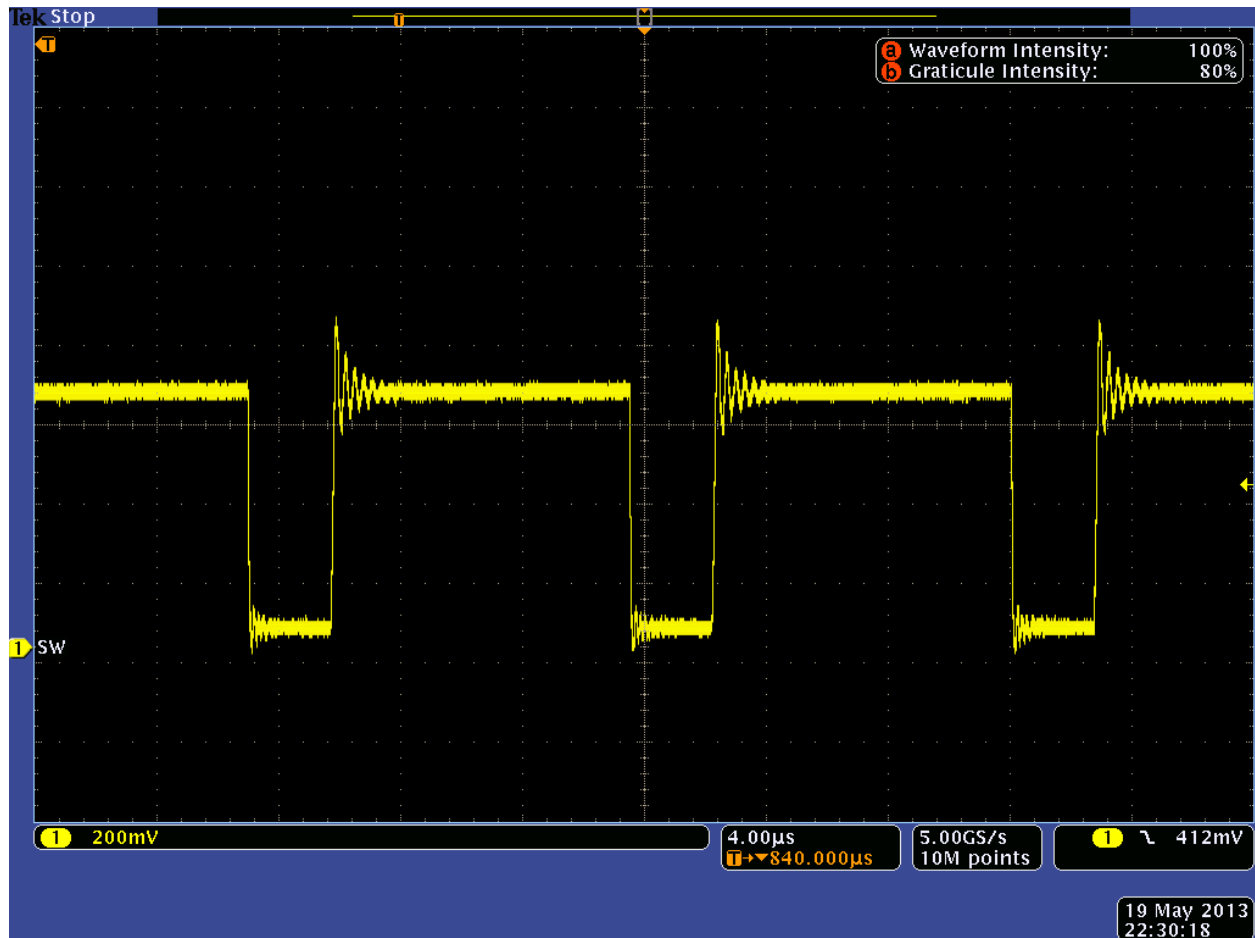
SW at 300Vin; 1.5A Load; (High Voltage probes used to attenuate signal; 1,000x Attenuation)



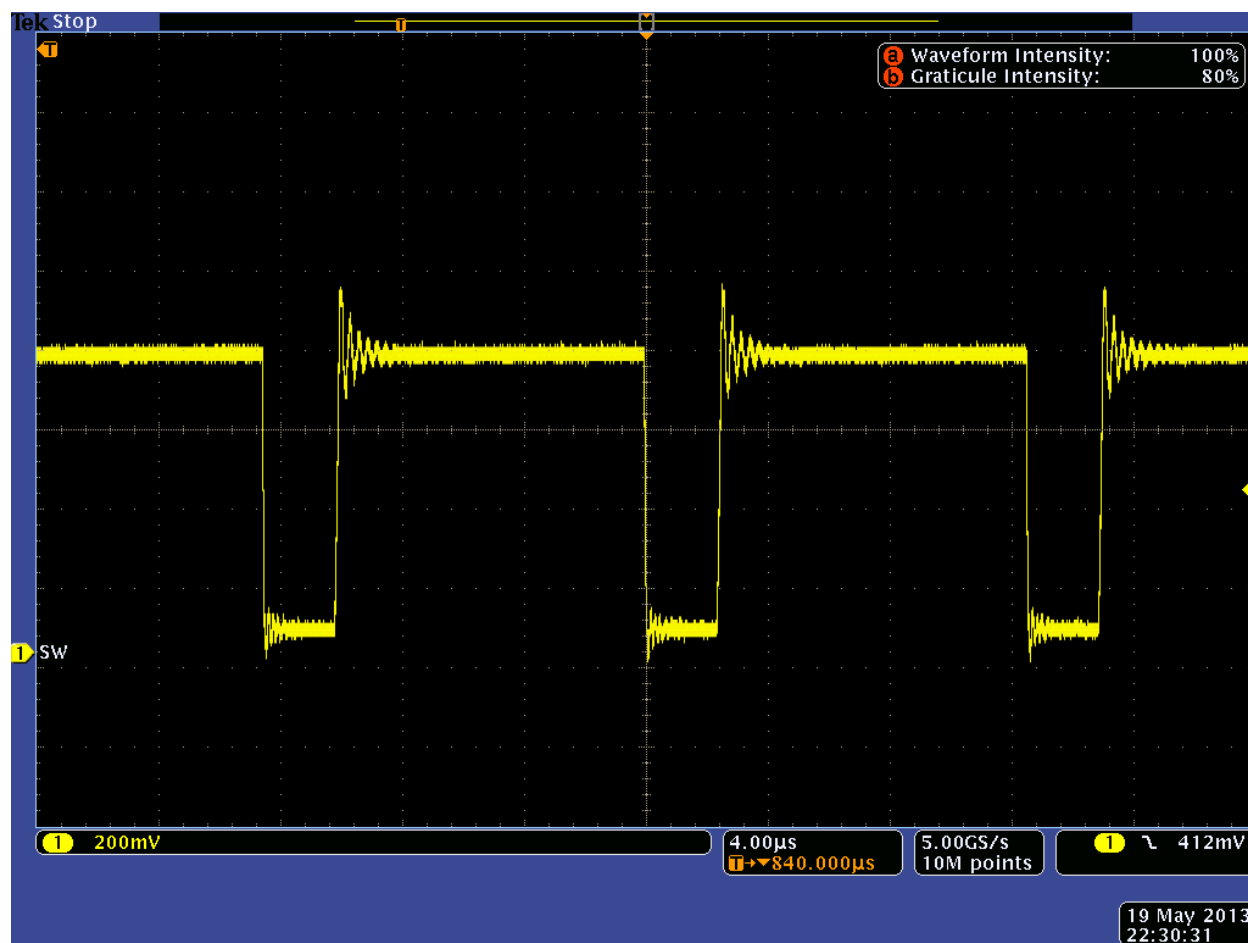
SW at 400Vin; 1.5A Load; (High Voltage probes used to attenuate signal; 1,000x Attenuation)



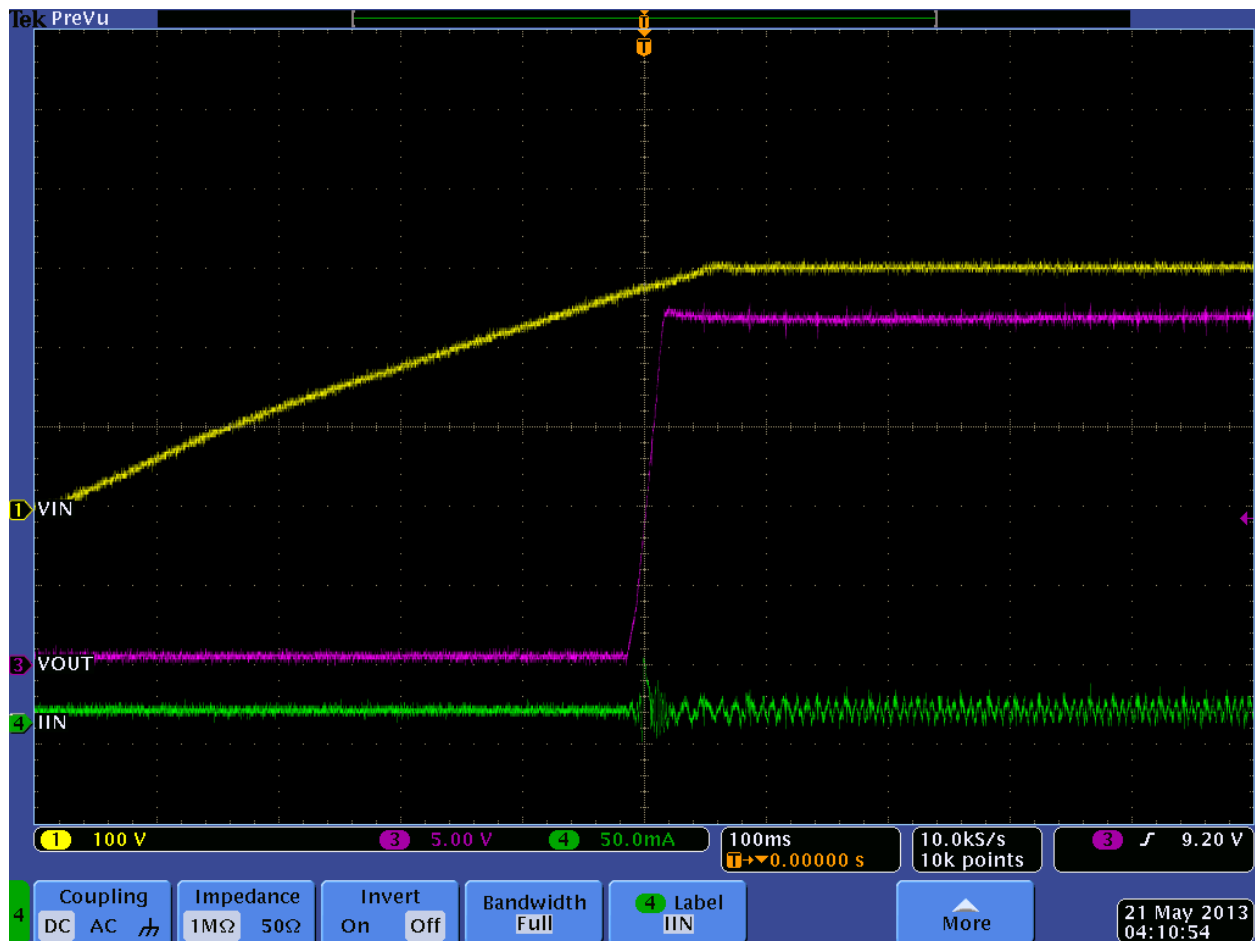
SW at 500Vin; 1.5A Load; (High Voltage probes used to attenuate signal; 1,000x Attenuation)



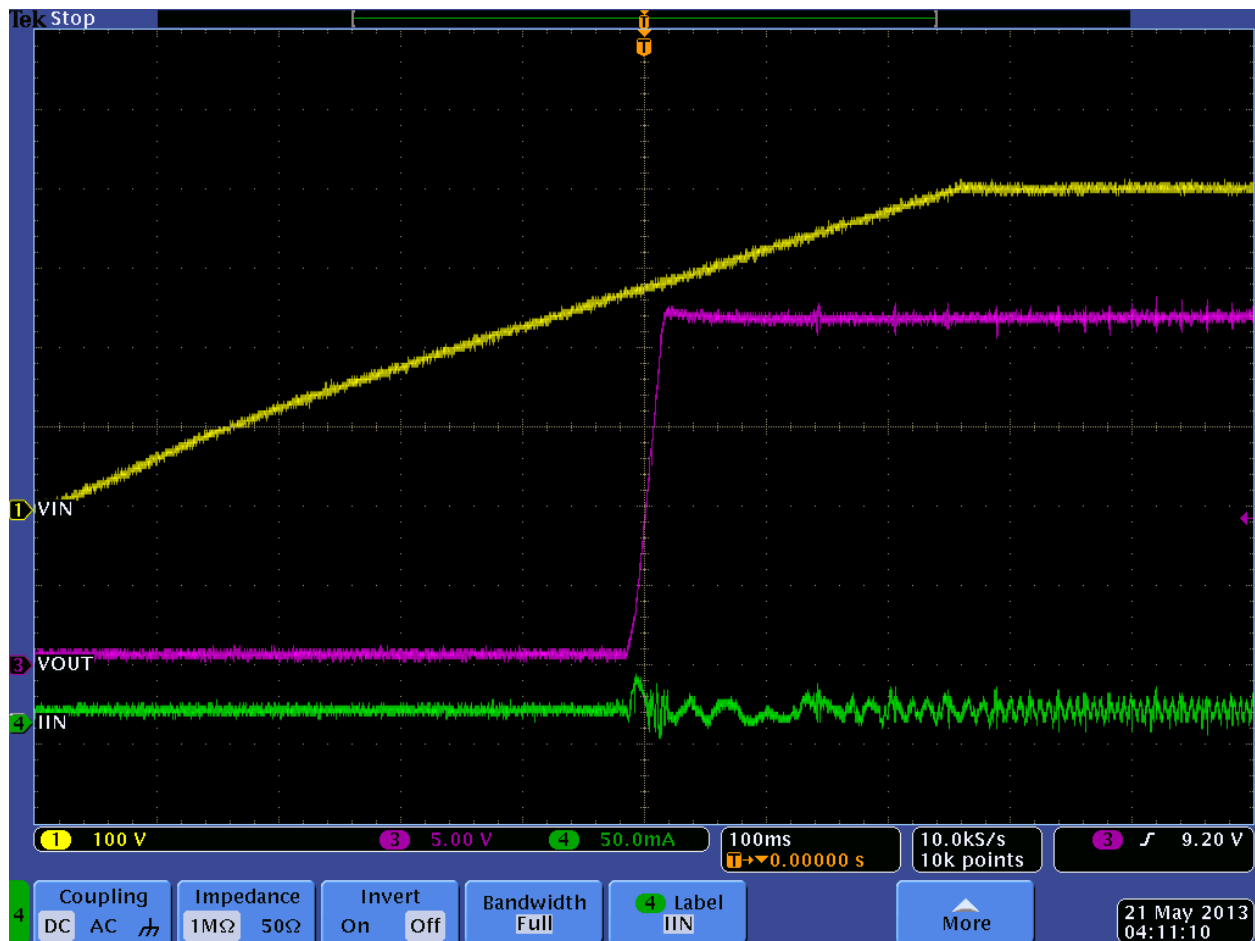
SW at 600Vin; 1.5A Load; (High Voltage probes used to attenuate signal; 1,000x Attenuation)



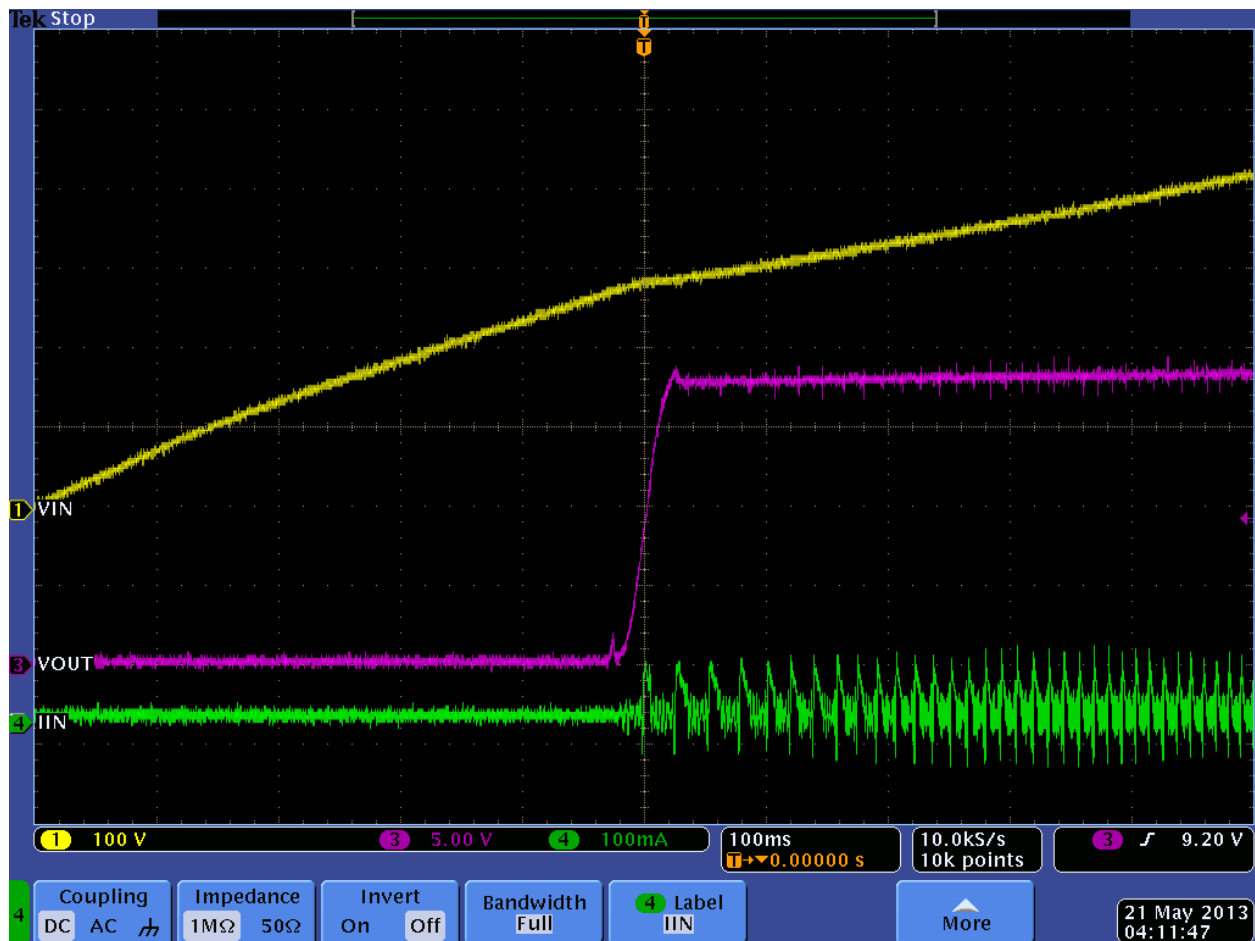
Startup at 300V_{in} and 0A Load



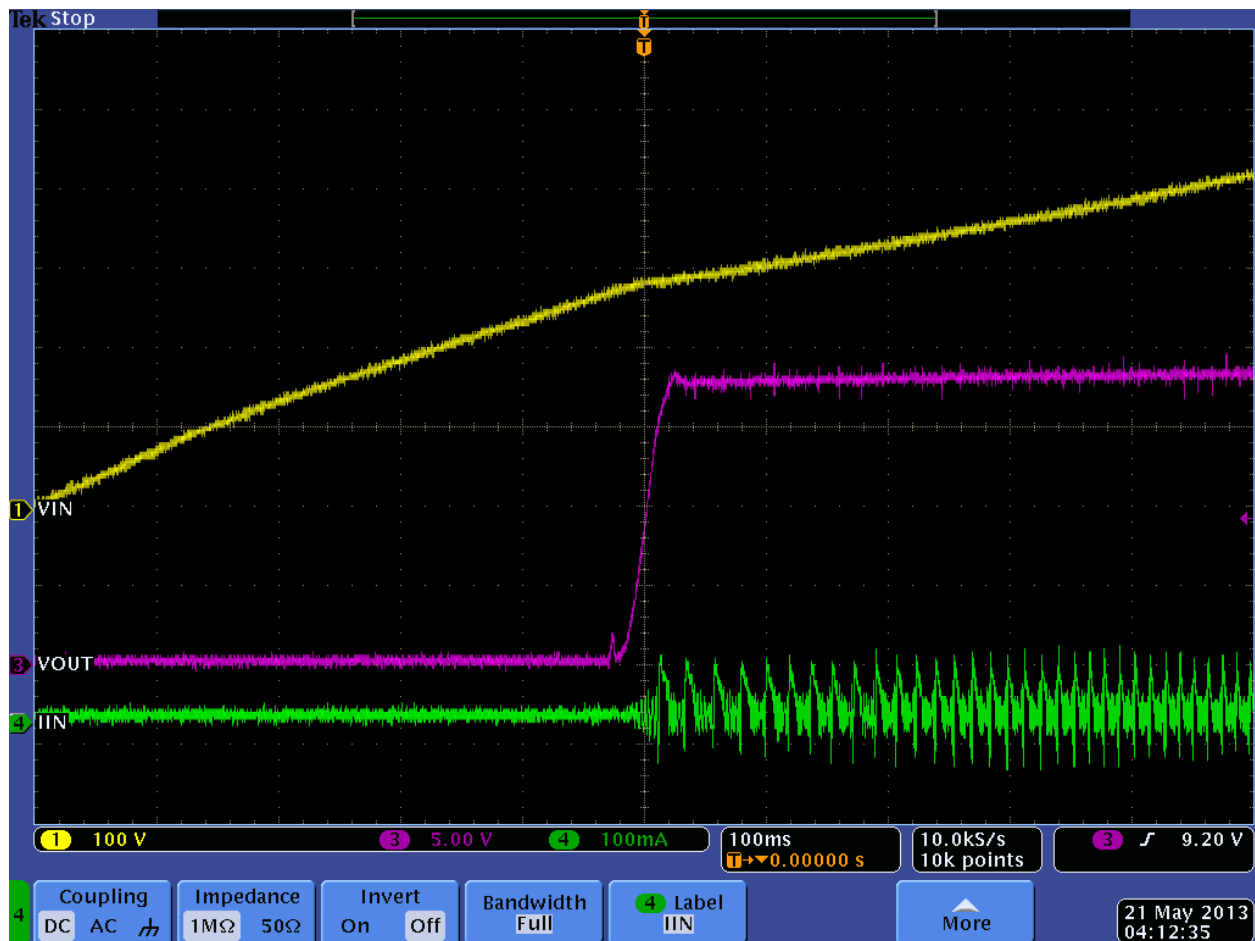
Startup at 400V_{in} and 0A Load



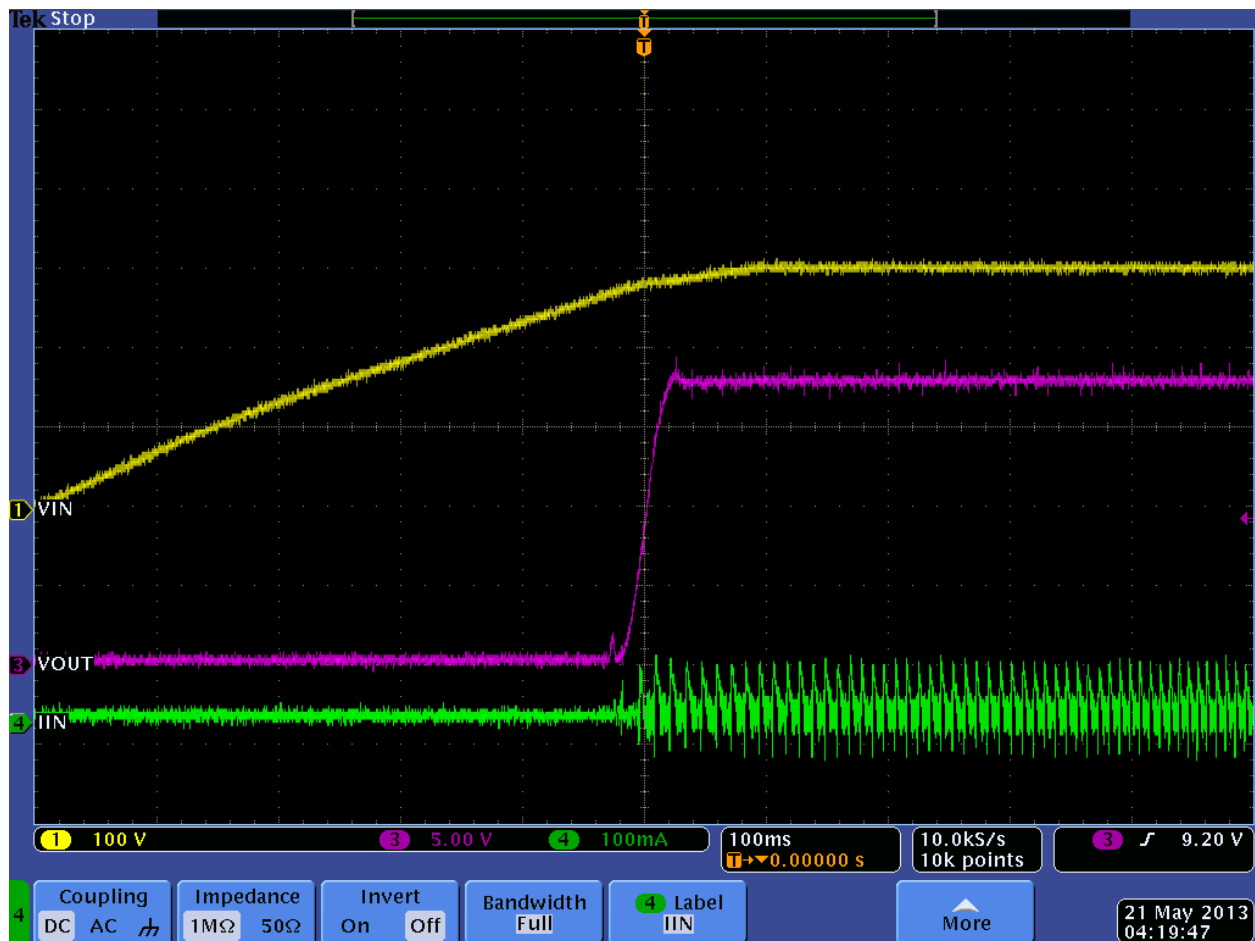
Startup at 500V_{in} and 0A Load



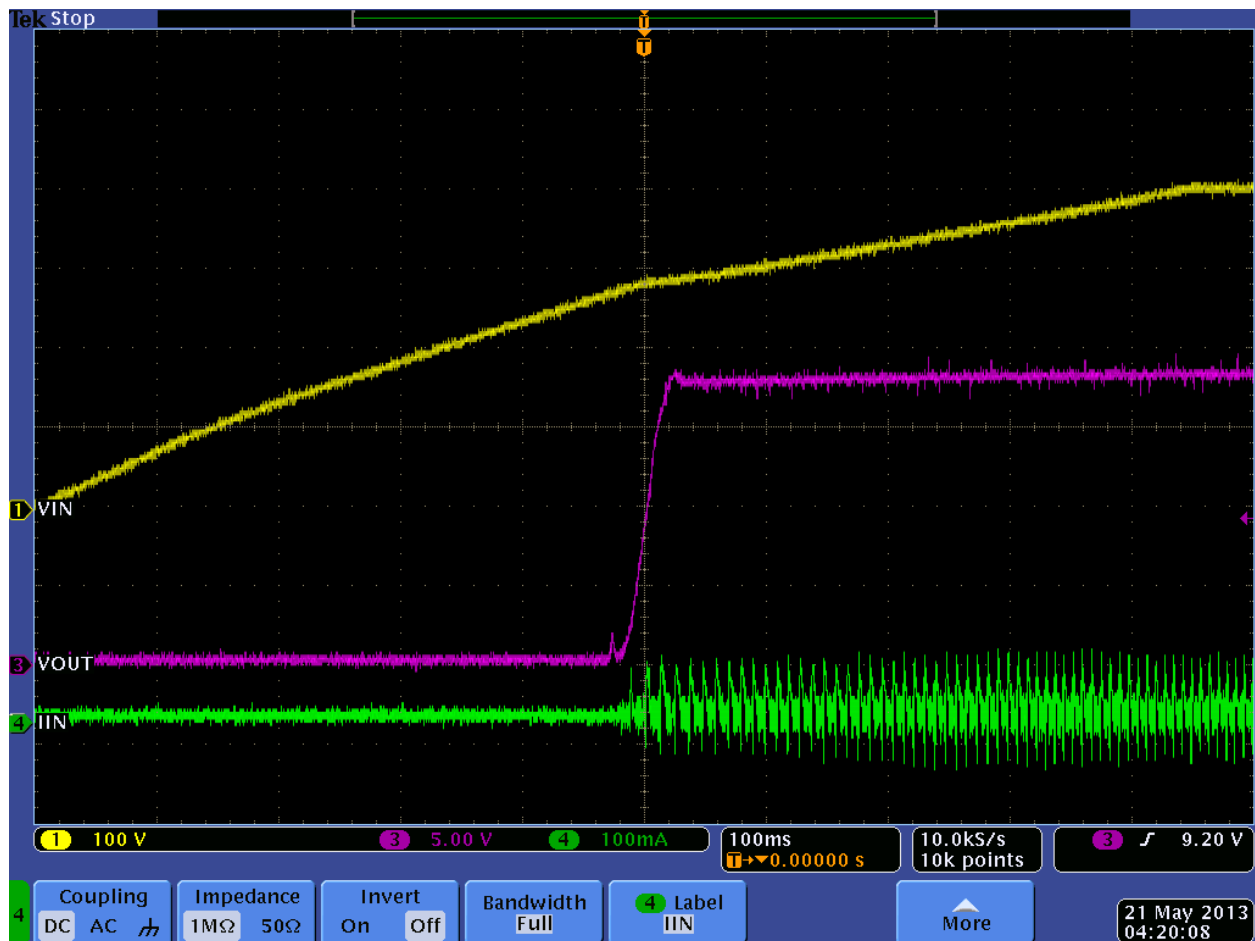
Startup at 600V_{in} and 0A Load



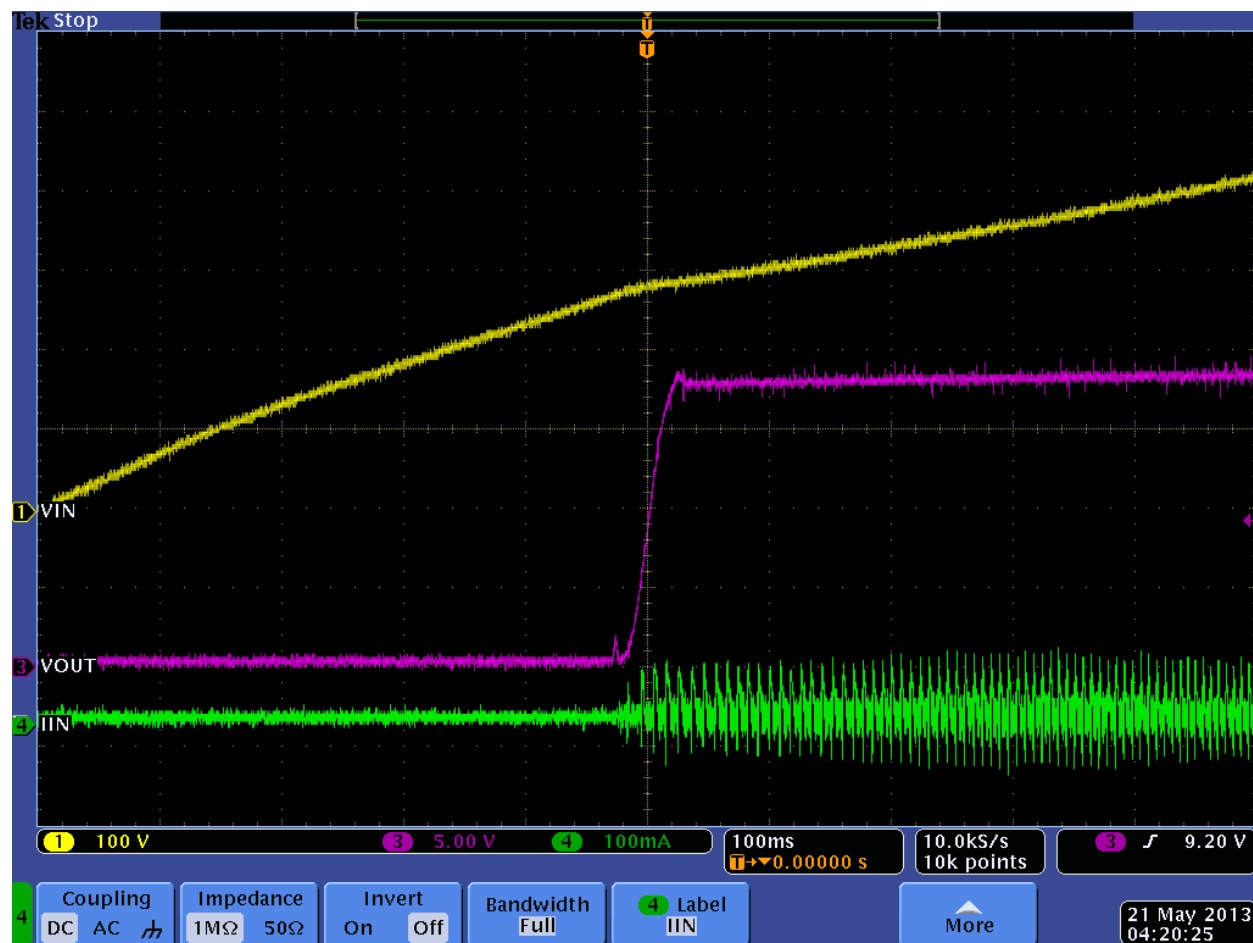
Startup at 300V_{in} and Full Load



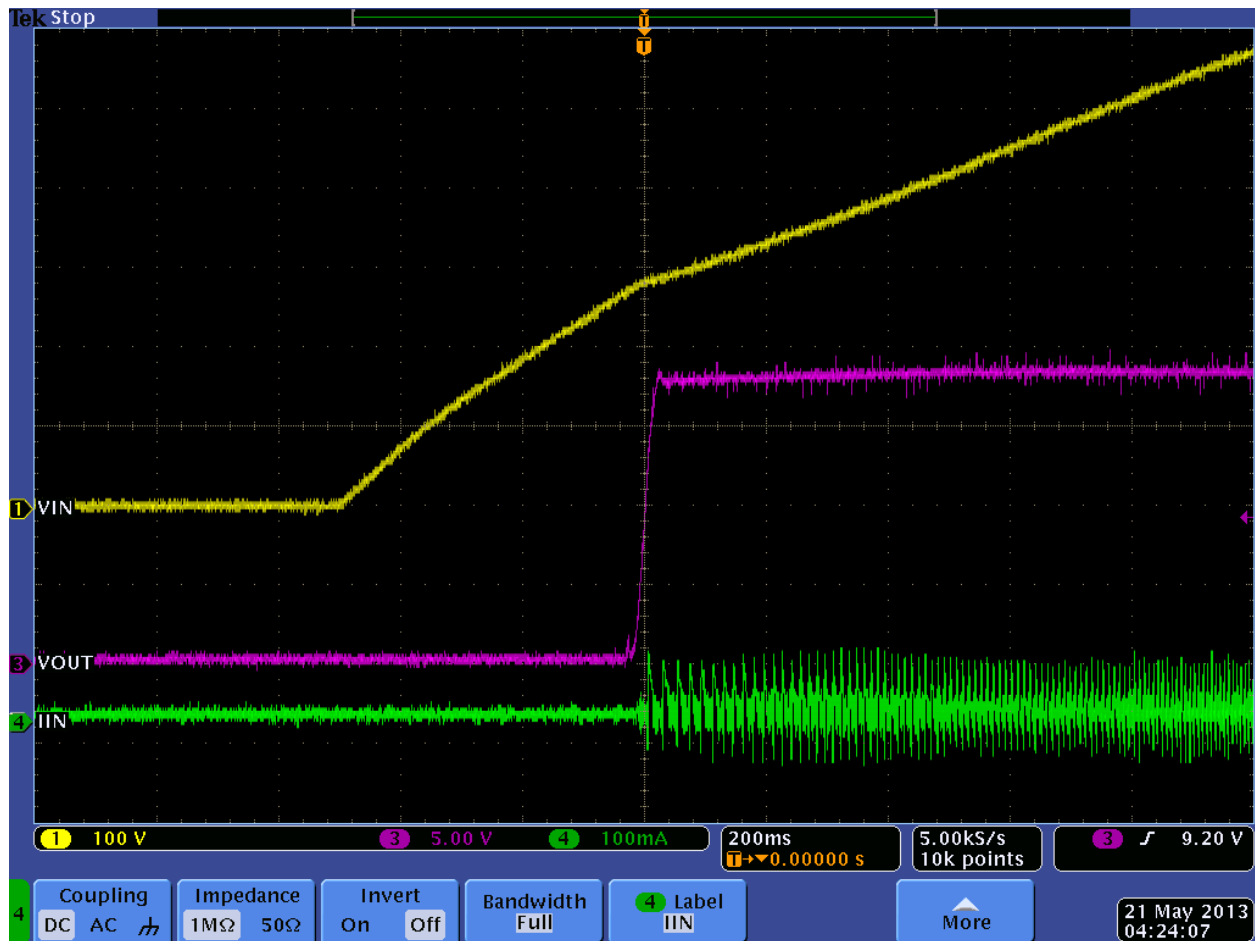
Startup at 400V_{in} and Full Load



Startup at 500V_{in} and Full Load



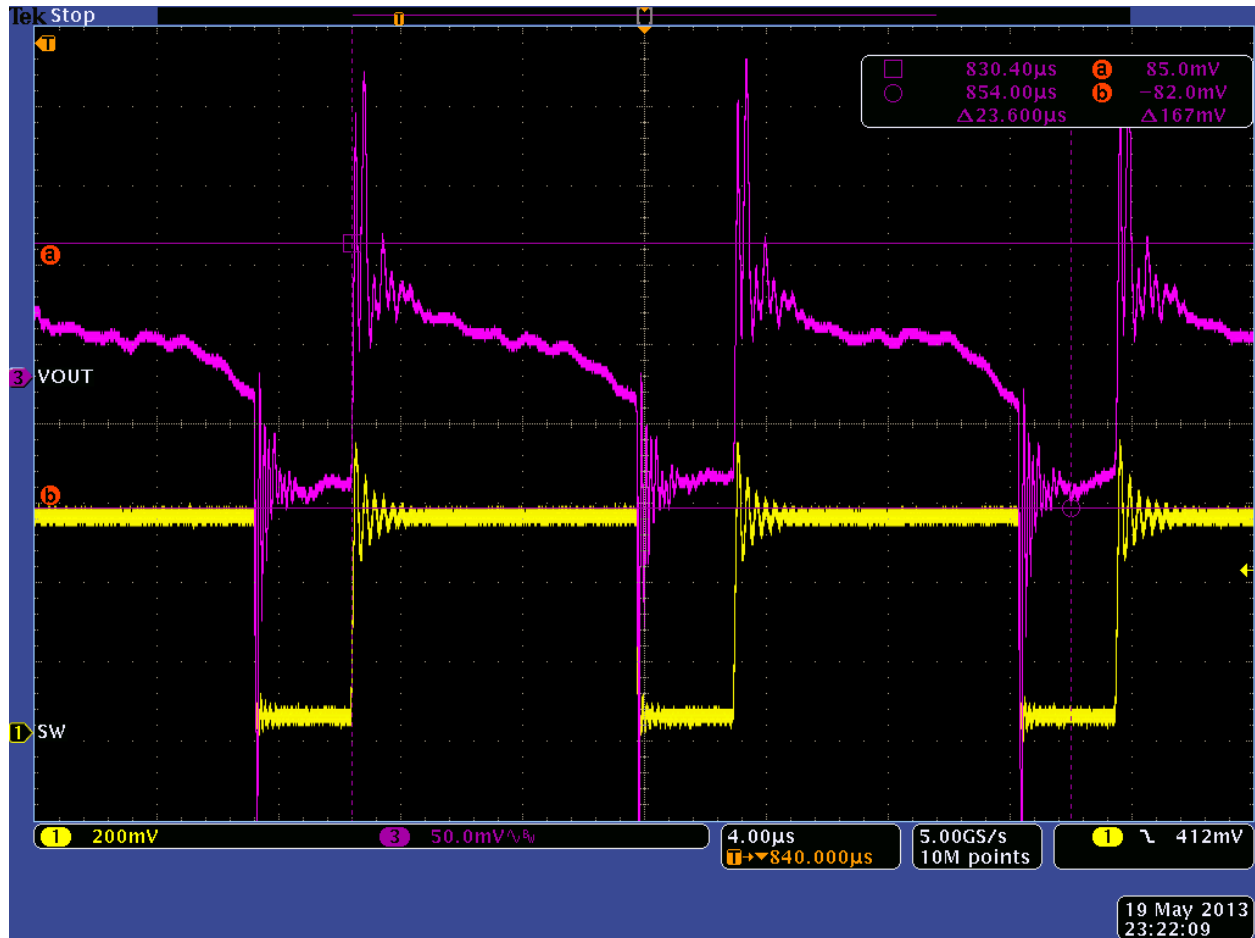
Startup at 600V_{in} and Full Load



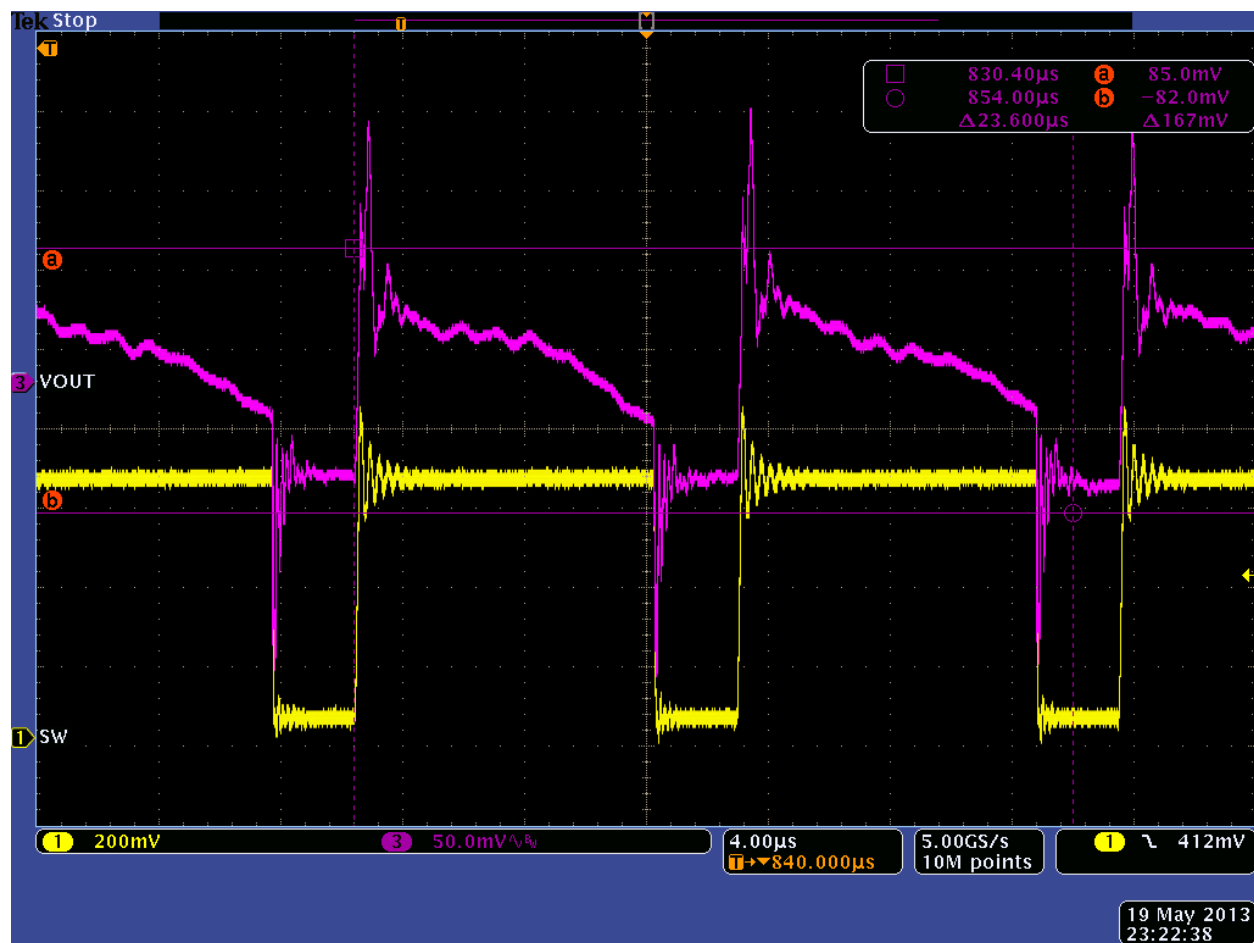
Ripple at 300Vin; 1.5A Load; (High Voltage probes used to attenuate signal; 1,000x Attenuation;
Cursors used for reference)



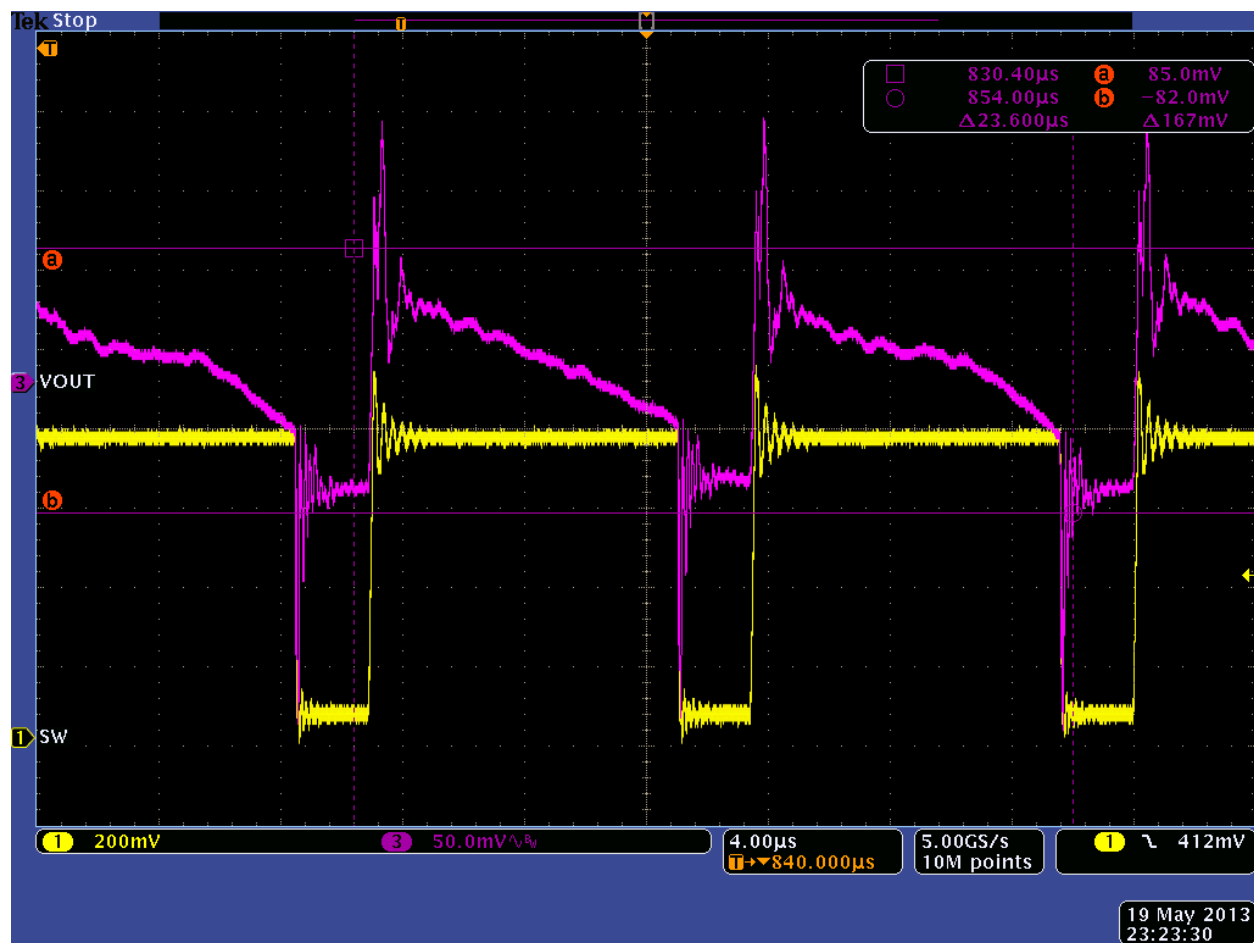
Ripple at 400V_{in}; 1.5A Load; (High Voltage probes used to attenuate signal; 1,000x Attenuation;
Cursors used for reference)



Ripple at 500V_{in}; 1.5A Load; (High Voltage probes used to attenuate signal; 1,000x Attenuation;
Cursors used for reference)



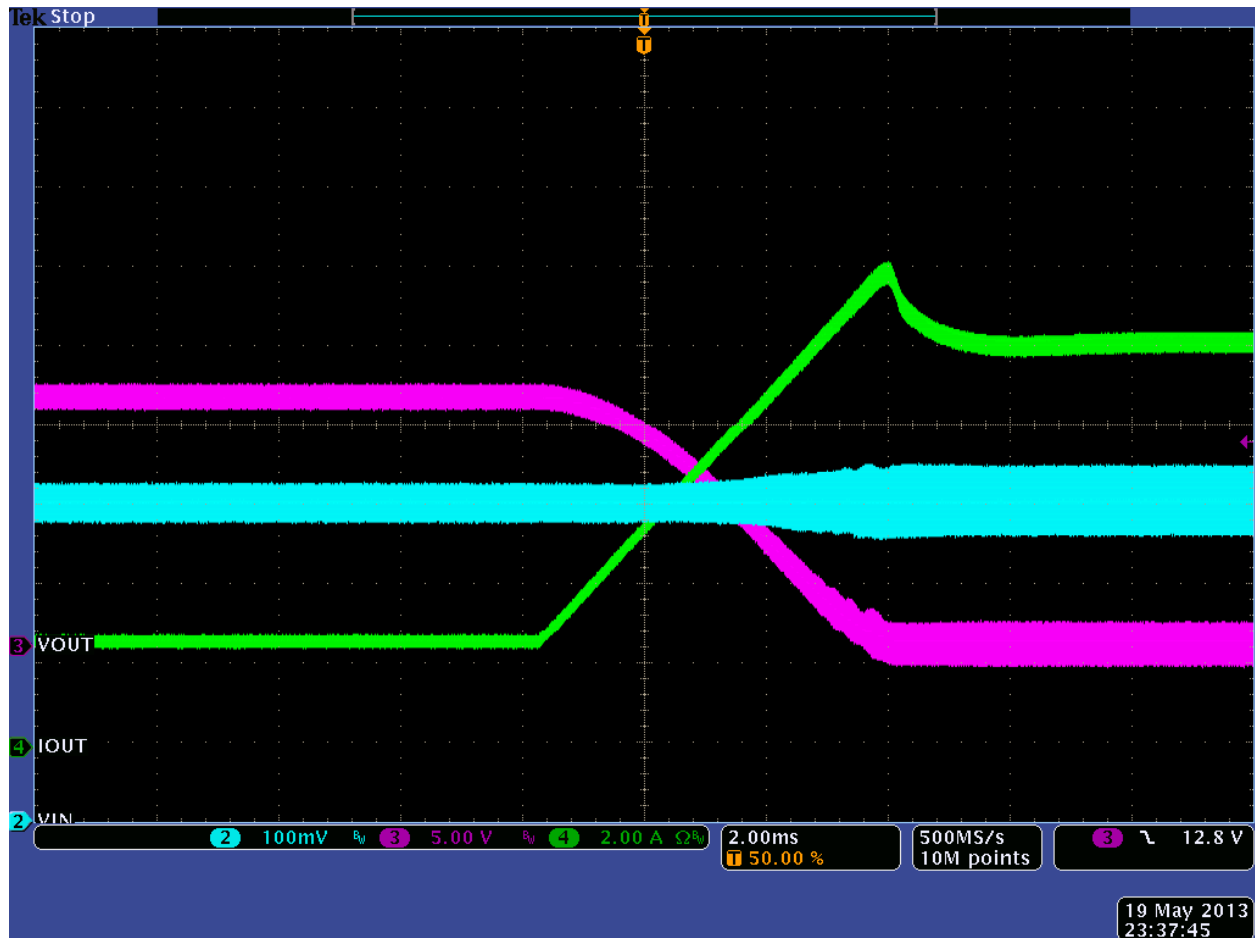
Ripple at 600V_{in}; 1.5A Load; (High Voltage probes used to attenuate signal; 1,000x Attenuation;
Cursors used for reference)



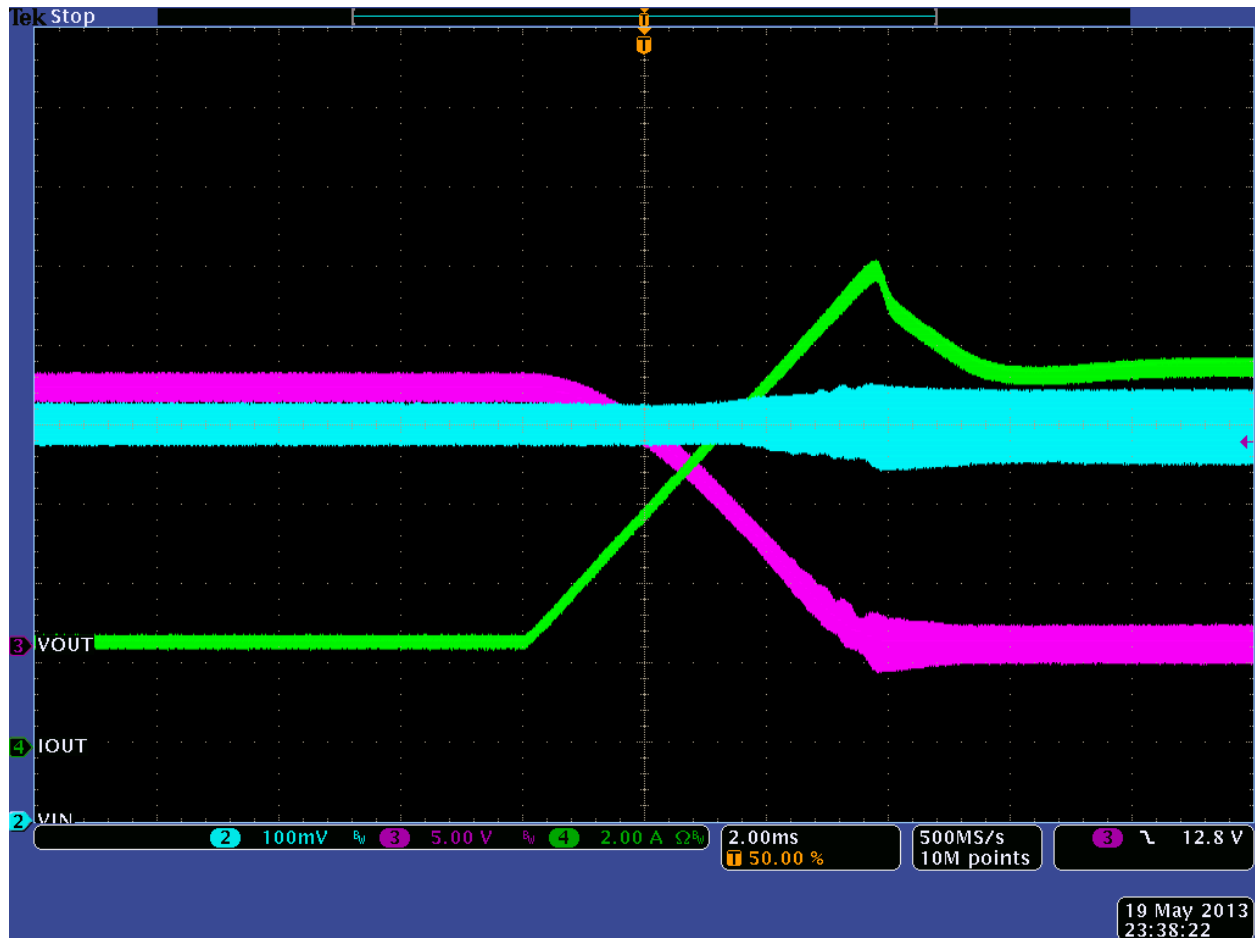
Short Circuit at 300V_{in} (High Voltage probes used to attenuate signal; 1,000x Attenuation)



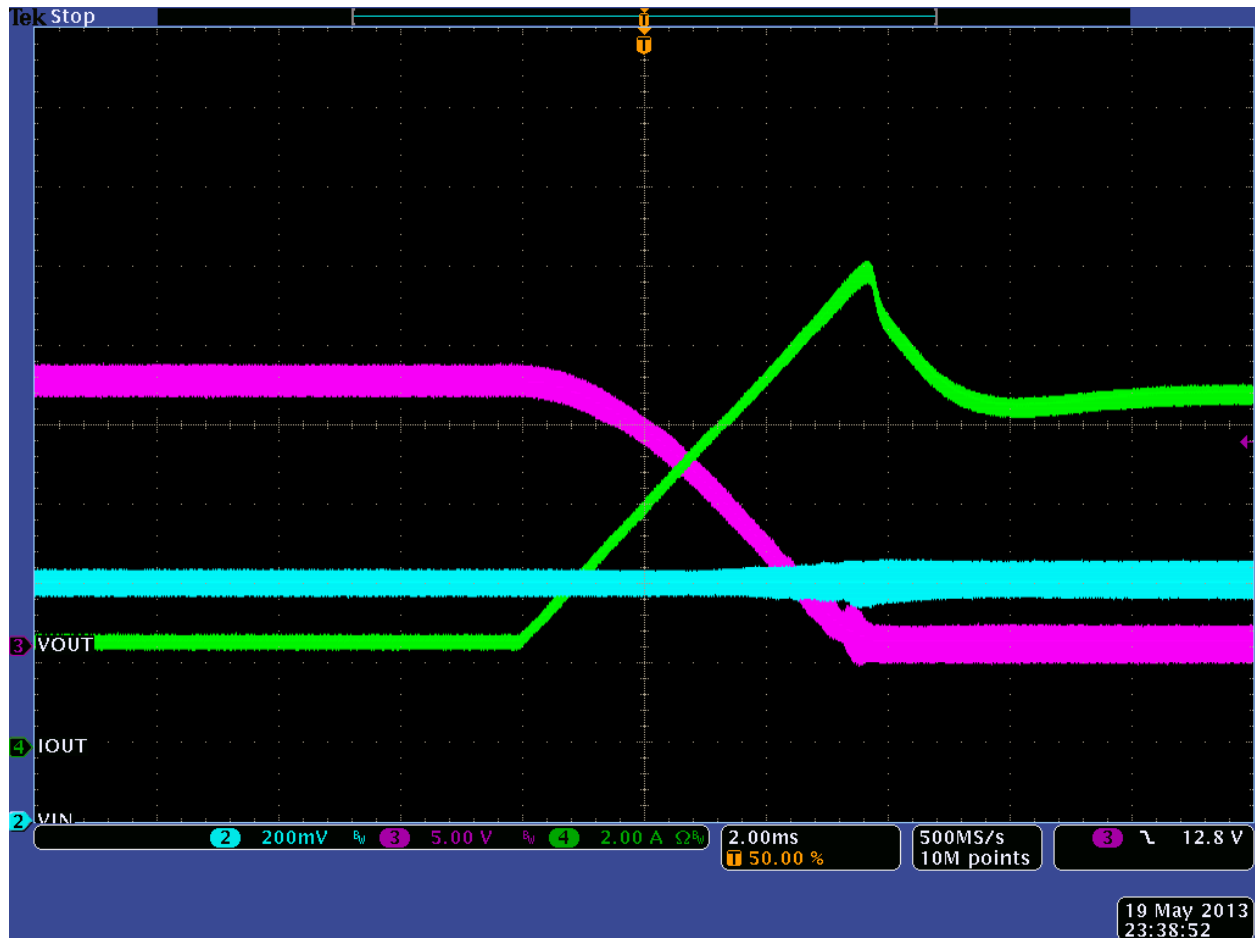
Short Circuit at 400V_{in} (High Voltage probes used to attenuate signal; 1,000x Attenuation)



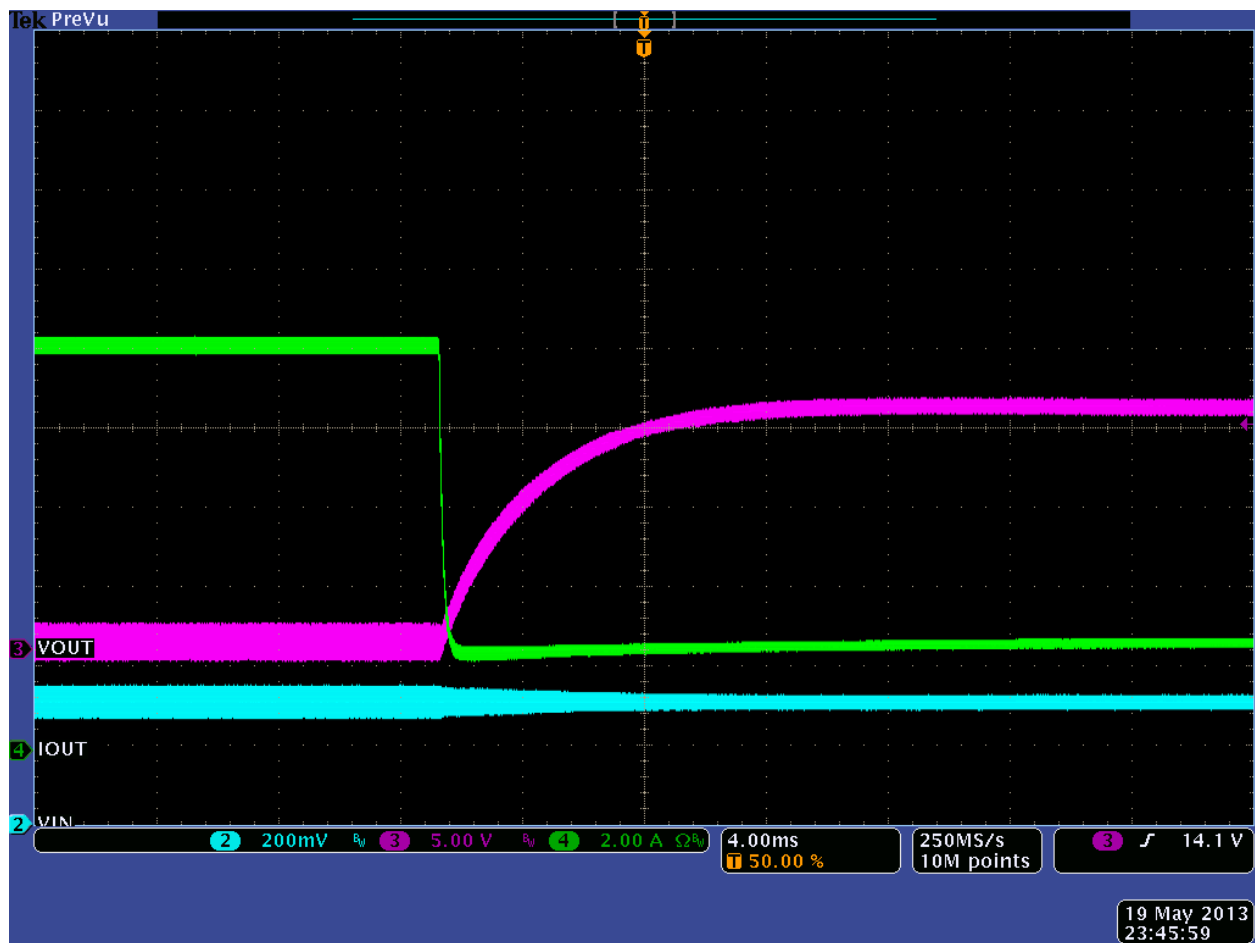
Short Circuit at 500V_{in} (High Voltage probes used to attenuate signal; 1,000x Attenuation)



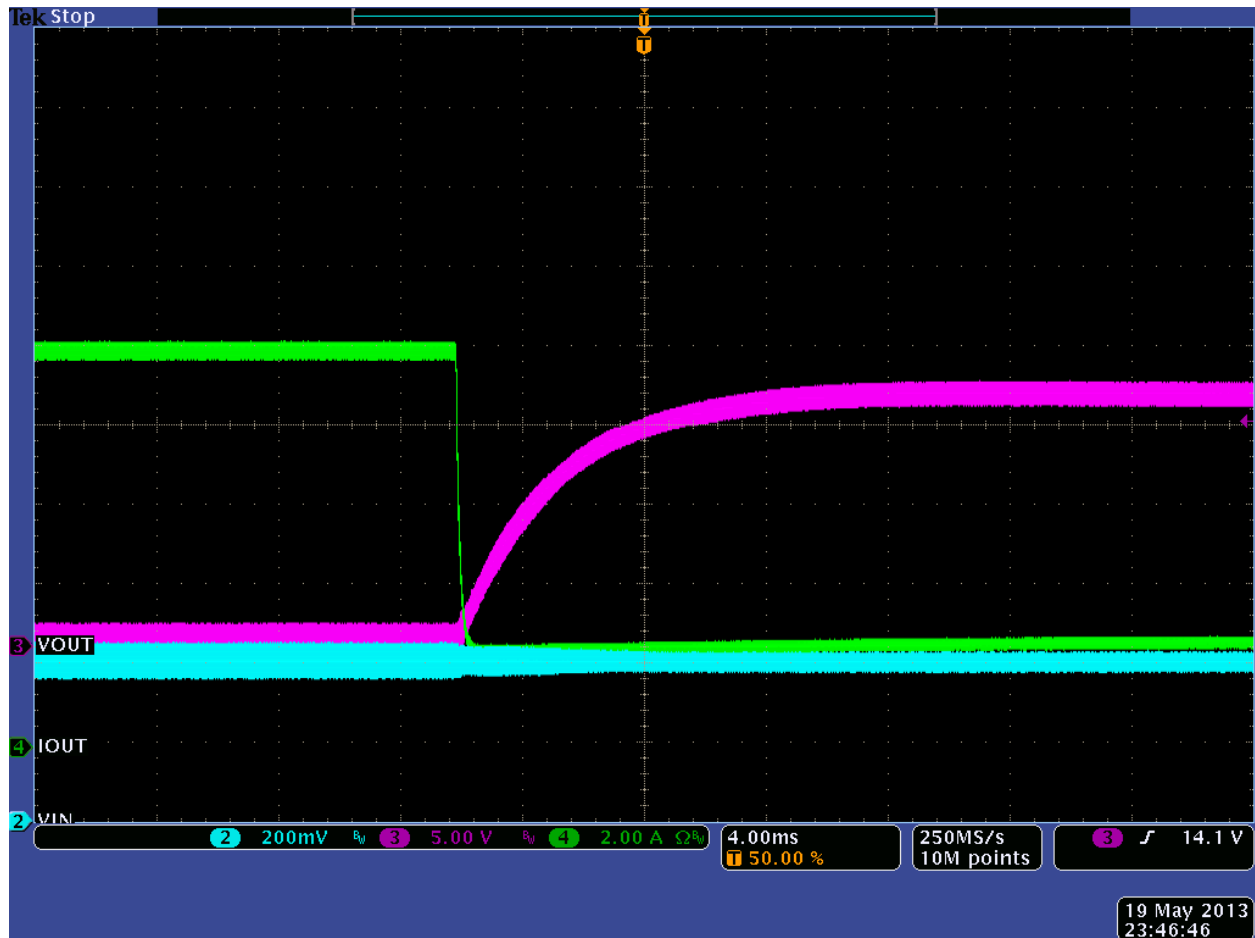
Short Circuit at 600V_{in} (High Voltage probes used to attenuate signal; 1,000x Attenuation)



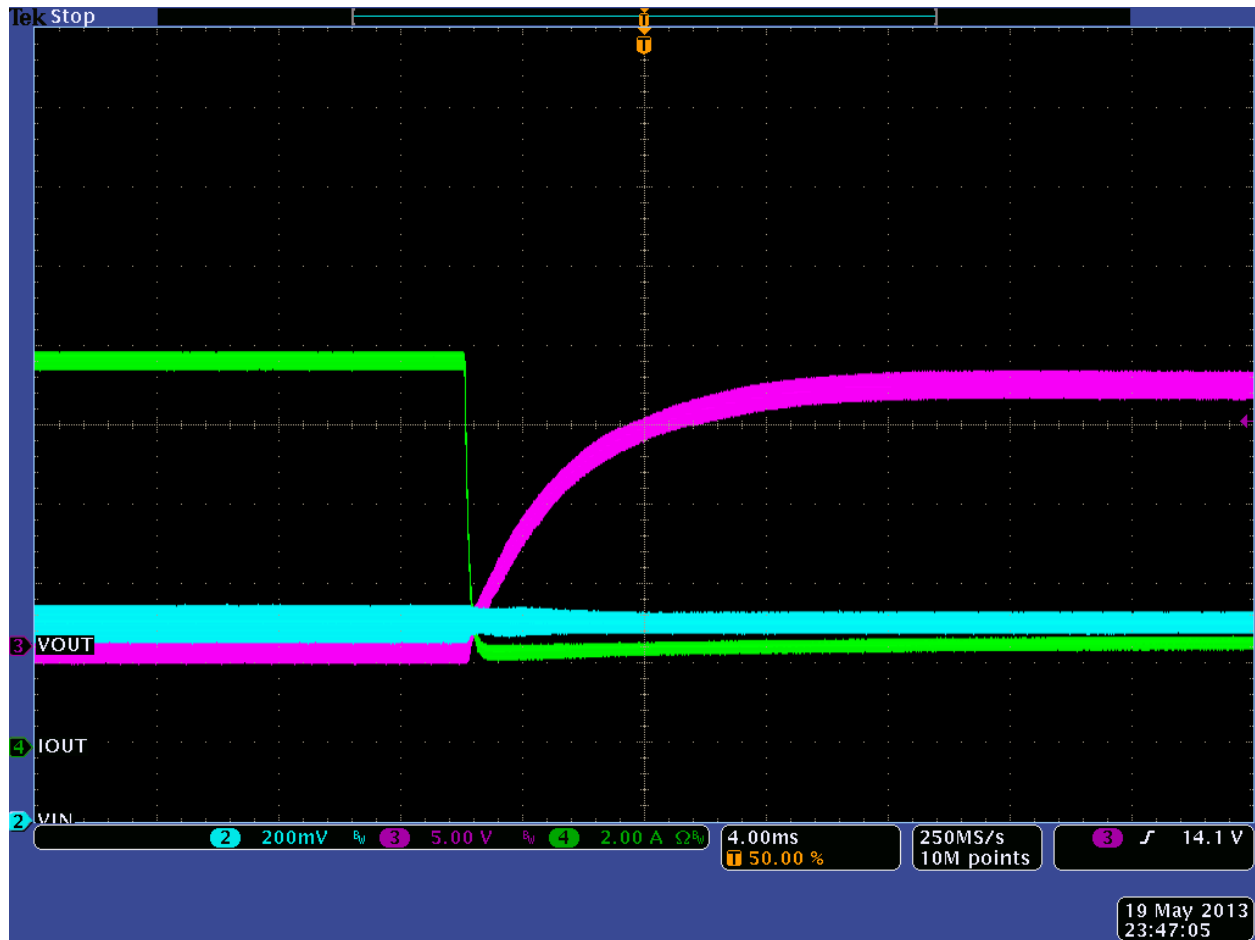
Short Circuit Recovery at 300Vin (High Voltage probes used to attenuate signal; 1,000x Attenuation)



Short Circuit Recovery at 400V_{in} (High Voltage probes used to attenuate signal; 1,000x Attenuation)



Short Circuit Recovery at 500V_{in} (High Voltage probes used to attenuate signal; 1,000x Attenuation)



Short Circuit Recovery at 600V_{in} (High Voltage probes used to attenuate signal; 1,000x Attenuation)



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